

RF ESD Protection Diodes

 ESD protection of RF antenna / interfaces or ultra high speed data lines acc. to: IEC61000-4-2 (ESD): ± 20 kV (air / contact) IEC61000-4-4 (EFT): 40 A (5/50 ns) IEC61000-4-5 (surge): 10 A (8/20 µs)



- Very low line capacitance: 0.8 pF @ 1 GHz
 (0.4 pF per diode)
- Ultra low series inductance: 0.4 nH per diode
- Very low clamping voltage
- Ultra small leadless package 1.2 x 0.8 x 0.39 mm
- Pb-free (RoHS compliant) package

Applications in anti-parallel configuration

 For low RF signal levels without superimposed DC voltage: e.g. GPS, XM-Radio, Sirius, DVB, DMB, DAB, Remote Keyless Entry

Applications in rail-to-rail configuration

- For high RF signal levels or low RF signal levels with superimposed DC voltage: e.g. HDMI, S-ATA, Gbit Ethernet
- For more technical details on ESD and Antenna protection please refer to Application Note No.103 on www.infineon.com/tvsdiodes



ESD0P8RFL



Туре	Package	Configuration	Marking
ESD0P8RFL	TSLP-4-7	anti-parallel	E8



Maximum Ratings at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Value	Unit
ESD contact discharge ¹⁾	V _{ESD}	20	kV
Peak pulse current $(t_p = 8 / 20 \mu s)^2$	I_{pp}	10	А
Operating temperature range	T_{op}	-55150	°C
Storage temperature	$T_{\rm stg}$	-65150	

Electrical Characteristics at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Characteristics -	·		•		•
Reverse working voltage ³⁾	V_{RWM}	-	-	50	V
Reverse current ³⁾	I _R	-	-	100	nA
V _R = 50 V					
Forward clamping voltage ²⁾	V_{FC}	-	12	15	V
I _{PP} = 10 A					
Line capacitance ⁴⁾	C _T	-	0.8	-	pF
$V_{R} = 0 \text{ V}, f = 1 \text{ GHz}$					
Series inductance (per diode)	LS	-	0.4	-	nH

¹V_{ESD} according to IEC61000-4-2, only valid in anti-parallel or rail-to-rail connection.

Please refer to the application examples.

 $^{^2}I_{
m DD}$ according to IEC61000-4-5, only valid in anti-parallel or rail-to-rail connection.

Please refer to the application examples.

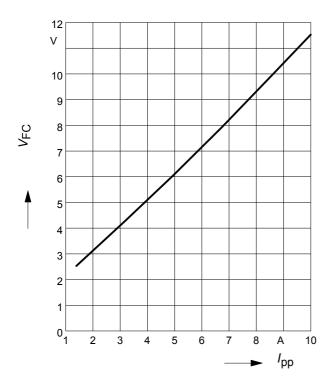
 $^{^3}$ Only valid in rail-to-rail configuration with $V_{\rm CC} \ge V_{\rm RWM}$

⁴Total capacitance line to ground (2 diodes in parallel)



Forward clamping voltage $V_{FC} = f(I_{PP})$

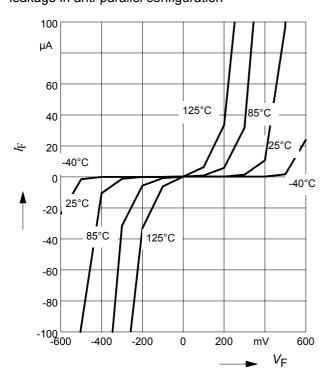
$$t_{\rm p}$$
 = 8 / 20 $\mu {\rm s}$



Forward current $I_F = f(V_F)$

T_A = Parameter

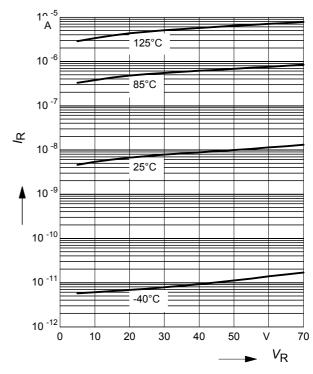
leakage in anti-parallel configuration



Reverse current $I_R = f(V_R)$

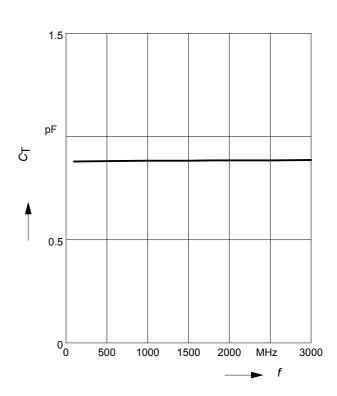
T_A = Parameter

leakage in rail-to-rail configuration



Line capacitance $C_T = f$ (f)

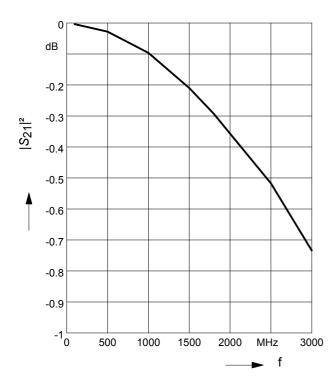
$$V_R = 0 V$$





Insertion loss $I_{L} = -|S_{21}|^2 = f(f)$

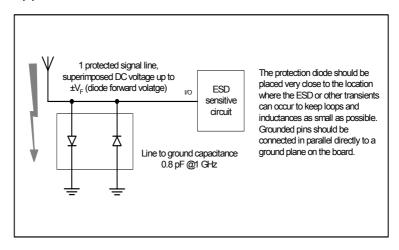
$$V_{\mathsf{R}}$$
 = 0 V, Z = 50 Ω





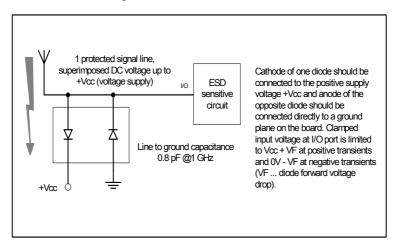
1. Application example

1 RF signal channel, anti-parallel configuration, please refer also to Application Note No.103



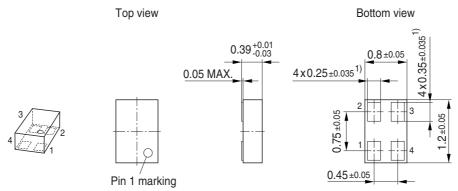
2. Application example

1 RF signal channel, rail-to-rail configuration





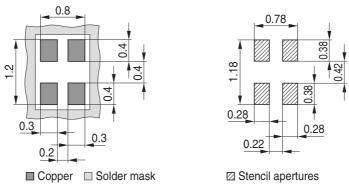
Package Outline



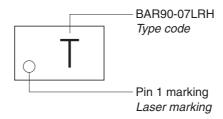
1) Dimension applies to plated terminal

Foot Print

For board assembly information please refer to Infineon website "Packages"

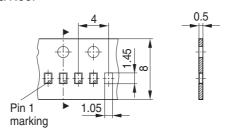


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel



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